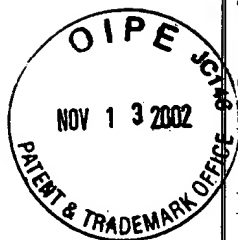


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Robert F. Darveaux et al.
Assignee: Amkor Technology, Inc.
Title: Embedded Heat Spreader Ball Grid Array
Serial No.: 09/923,834 Filing Date: August 7, 2001
Examiner: Erdem, Fazli Group Art Unit: 2826
Docket No.: M-10966 US



#7
Amkt
a
11/20/02
arg

San Jose, California
November 23, 2002

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION MAILED ON 6/10/2002

RECEIVED
NOV 20 2002
TECHNOLOGY CENTER 2800

Dear Sir:

This communication is responsive to the Office Action mailed June 10, 2002 for the above-referenced application. Applicant respectfully requests that the Examiner reconsider the claims in view of the amendments and remarks set forth below.

IN THE CLAIMS

This submission amends claims 4, 6, 8, 9, 11, 14-18, and 20-22, and adds new claims 24-47. The amendments to the claims are shown in an Appendix hereto, entitled "Version with Markings to Show Changes Made." Below is a list of all of the now-pending claims.

11/18/2002 AADOF01

00000076 192386 09923834

01 FC:1202

42.00 CH

432

1. A semiconductor die package, comprising:

a substrate having a first and a second surface;

a die having a first surface and a second surface, wherein the first surface of

the die is attached to the first surface of the substrate;

a heat spreader attached to the second surface of the die; and

LAW OFFICES OF
SKJERNEN MORRILL LLP

25 METRO DRIVE
SUITE 700
SAN JOSE, CA 95110
(408) 453-9200
FAX (408) 453-7979